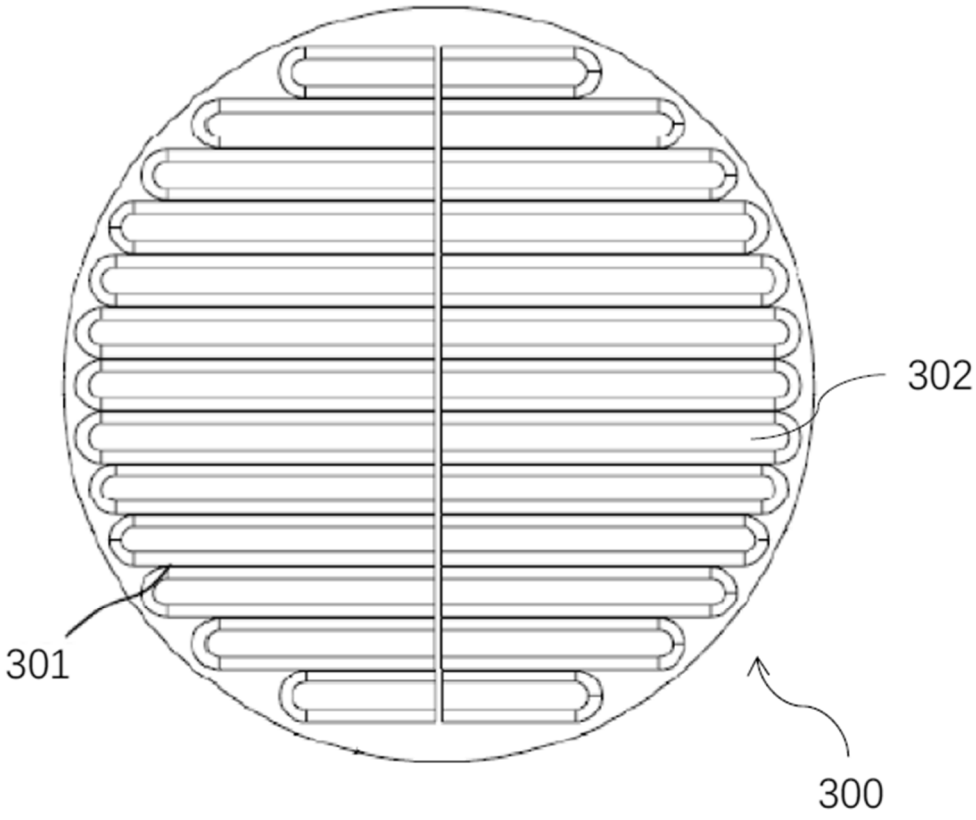


FIG. 4

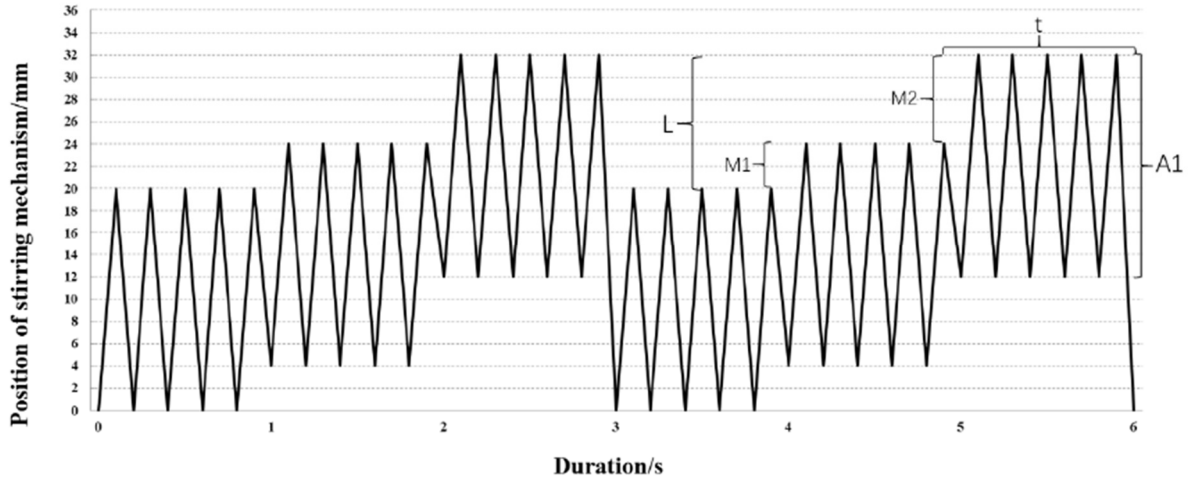

Position of stirring mechanism/mm
Duration/s
t
M2
L
M1
A1

FIG. 5

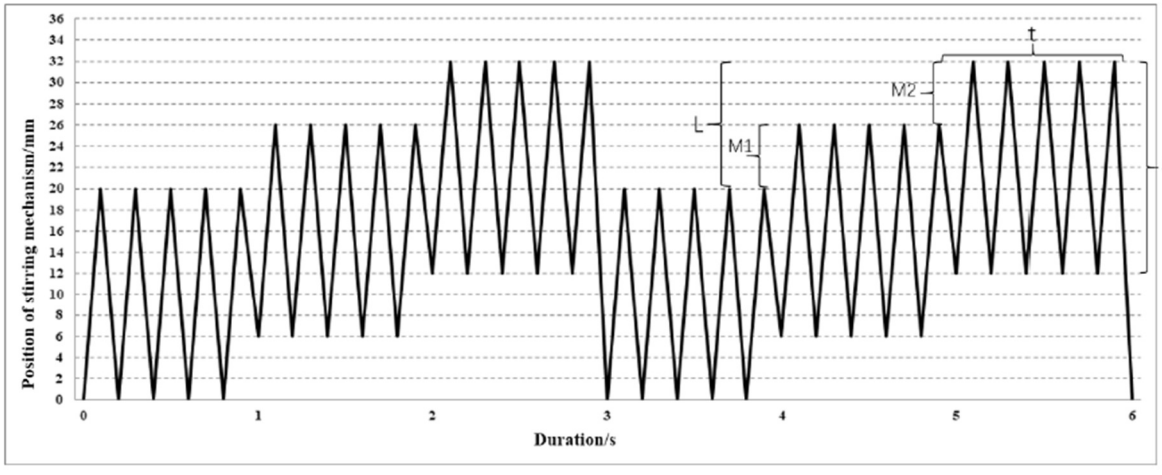

Position of stirring mechanism/mm
Duration/s
t
M2
L
M1
A1

FIG. 6

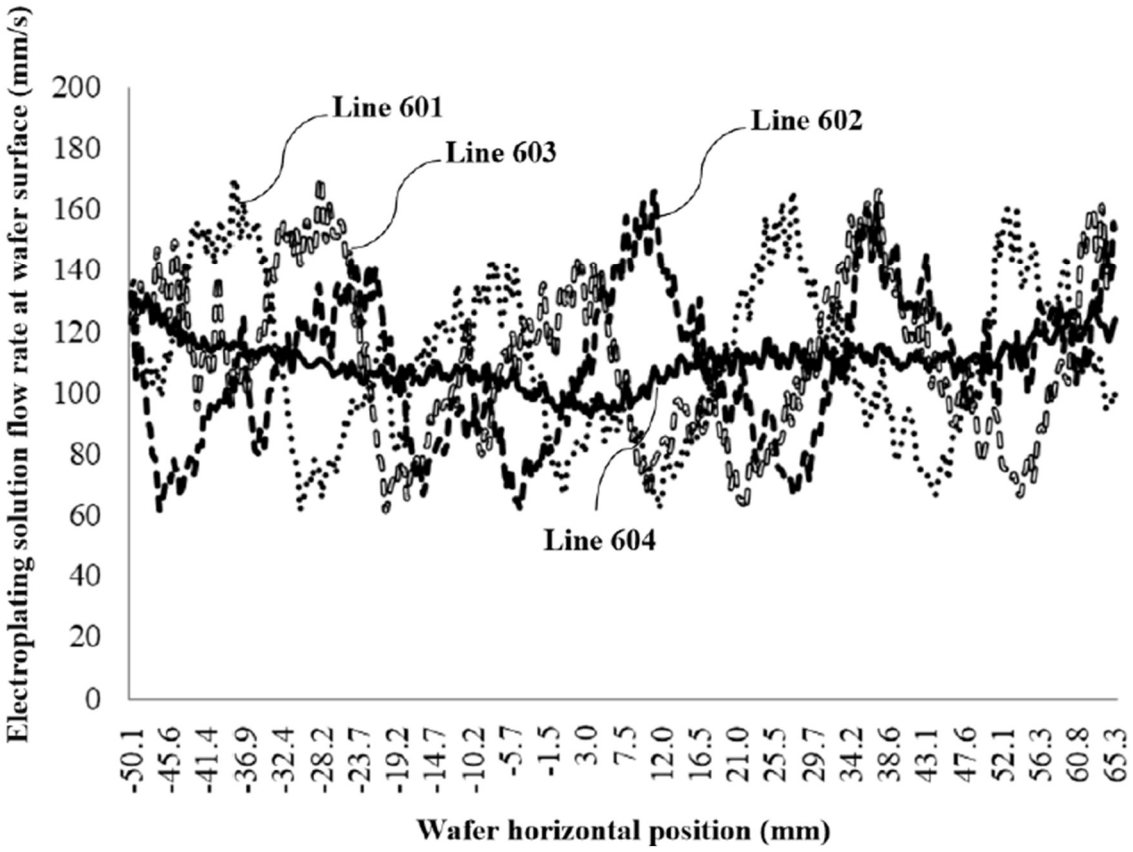

Electroplating solution flow rate at wafer surface (mm/s)
200
180
160
140
120
100
80
60
40
20
0
Line 601
Line 603
Line 602
Line 604
-50.1
-45.6
-41.4
-36.9
-32.4
-28.2
-23.7
-19.2
-14.7
-10.2
-5.7
-1.5
3.0
7.5
12.0
16.5
21.0
25.5
29.7
34.2
38.6
43.1
47.6
52.1
56.3
60.8
65.3
Wafer horizontal position (mm)

FIG. 7